

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	961	(361/707).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/07 09:21
L2	814	L1 and @pd< "20031205"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/07 12:53
L3	69	I2 and (plasma or LCD or LED)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/07 09:50
L4	15	I2 and plasma	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/07 09:51
L5	5	("5971566" "5990618" "6198222").PN. OR ("6373702").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/03/07 10:25
L6	5626	(plasma with display) and (substrate or circuit\$1board) and heat	US-PGPUB; USPAT; USOCR	OR	ON	2006/03/07 10:26
L7	4378	(plasma adj display) and (substrate or circuit\$1board) and heat	US-PGPUB; USPAT; USOCR	OR	ON	2006/03/07 10:27
L8	2500	(plasma adj display) and (substrate or circuit\$1board) and heat and plate and metal	US-PGPUB; USPAT; USOCR	OR	ON	2006/03/07 10:27
L9	791	(plasma adj display) and (substrate or circuit\$1board) and heat and plate and metal and ((electronic adj circuit) or chip or (electronic adj device))	US-PGPUB; USPAT; USOCR	OR	ON	2006/03/07 10:28
L10	343	L9 and @pd< "20031205"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/07 12:38

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L11	2156	L7 and @pd< "20031205"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/07 12:38
L12	26	I11 and (copper with thermal)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/07 12:52
L13	0	(thermal adj interface adj (material or film)) with (spring or compliant or stiffness) with (copper)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/07 12:53
L14	64	(thermal adj interface adj (material or film)) with (spring or compliant or stiffness) and (copper)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/07 12:53
L15	25	L14 and @pd< "20031205"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/07 12:54
S1	942	(361/707).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/07 09:21
S2	381241	(circuit or mother) adj board	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/29 12:41
S4	5	S1 and S3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/29 12:42

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S5	581	S1 and S2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/29 12:45
S6	331	S5 and cool\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/29 12:46
S7	4450	plasma and ((electronic adj device) or (electronic adj circuit) or (electronic adj chip) or (electronic adj component) or ((mother\$1board or circuit\$1board) adj component)) and cool\$3 and (enclosure or frame or chassis or cover)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/29 14:41
S8	1734	S7 and (circuit or mother) and board	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/29 14:41
S9	673	S7 and ((heat adj sink) or (thermal adj plate))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/29 14:42
S10	2	("5268815").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/03 09:32
S11	4	((("6233150") or ("6188567"))).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/03 10:30
S12	0	("200500778446").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/03 10:31

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S13	2	("0778446").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/03 10:31
S14	1	10/953340	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/03 10:41
S15	125	(heat adj sink) and (retention adj module) and ((mother or circuit) adj board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/03 10:43
S16	25895	intel .as.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/03 10:43
S17	15	S15 and S16	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/03 10:43
S18	21	(heat adj sink) and (retention adj module) and S16	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/03 11:28
S19	2	("5268815").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/03 12:27
S20	1292	(361/687).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/03 12:27

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S21	18	(plasma) and S20	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/03 12:27
S22	0	(10/953340).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/01 10:51
S23	1	10/953340	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 10:57
S24	960	(361/707).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/01 12:38
S25	1370	(361/687).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/01 15:20
S26	2	(plasme adj display)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 12:40
S27	51962	(plasma adj display)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 12:40
S28	4836	plasma and ((electronic adj device) or (electronic adj circuit) or (electronic adj chip) or (electronic adj component) or ((mother\$1board or circuit\$1board) adj component)) and cool\$3 and (enclosure or frame or chassis or cover)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 12:48

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S30	41266	(plasma with (device or display or monitor)) .ti.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 12:44
S31	20	S30 and S28	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 12:50
S32	4836	plasma and ((electronic adj device) or (electronic adj circuit) or (electronic adj chip) or (electronic adj component)) and cool\$3 and (enclosure or frame or chassis or cover)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 12:50
S33	8313	plasma and ((electronic adj device) or (electronic adj circuit) or (electronic adj chip) or (electronic adj component)) and cool\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 12:50
S34	46	S30 and S33	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 12:50
S35	26	S34 not S31	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 12:50
S36	931	S25 and @pd< "20031205"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 15:21
S37	961	(361/707).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/02 14:50

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S38	814	S37 and @pd< "20031205"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/02 16:32
S39	14300	(multi\$1chip adj module)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/02 15:17
S40	41	(mother\$1board with chassis with attach\$4) and (fastener or screw or stand\$1off) and heat	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/02 15:10
S41	143	(mother\$1board with chassis with attach\$4) and (fastener or screw or stand\$1off)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/02 15:11
S42	145	S41 notl4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/02 15:11
S43	102	S41 not S40	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/02 15:14
S44	40	S43 and @pd< "20020111"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/02 15:27
S45	7628	S39 and package	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/02 15:18

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S46	5076	S45 and @pd< "20031205"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/02 15:18
S47	1715	((mother\$1board or circuit\$1board or substrate or package) and (heat or thermal) with (conduct\$3) with (post or stud or terminal or jumper) and solder)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/02 15:26
S48	836	S47 and @pd< "20020111"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/02 15:27
S49	2	("5548090").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/02 16:32
S50	2	10/792231	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/06 12:59